



PATENT
ATTY. DOCKET NO.: P67426US0

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Joon Ki HONG

Group Art Unit: 2814

Serial No.: 10/017,318

Examiner: Nathan Ha

Filed: December 18, 2001

For: STACK CHIP MODULE WITH ELECTRICAL CONNECTION AND ADHESION OF
CHIPS THROUGH A BUMP FOR IMPROVED HEAT RELEASE CAPACITY

AMENDMENT UNDER RULE 1.111

Commissioner of Patents
Washington, D.C. 20231

Sir:

In response to the Office Action (Paper No. 6) dated January 24, 2003, kindly
amend the above-identified patent application as follows:

IN THE SPECIFICATION:

On page 2, the third full paragraph beginning on line 11, has been amended to
read as follows:

--Fig. 1 is a cross sectional view showing a conventional stack package according
to a first method. As shown in Fig. 1, two semiconductor packages 10a, 10b are arranged in a
stacked arrangement wherein an outer lead of the top package 10a is bonded to that of the bottom
package 10b. In the packages 10a, 10b, lead frames 4a, 4b are adhered on one side of each
semiconductor chip 1a, 1b by adhesives 3a, 3b, all respectively. Inner leads of each lead frame
4a, 4b are electrically connected to bonding pads 2a, 2b of each semiconductor chip 1a, 1b by

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31